Pa0nhc RF power meter 20171220

Soldering strateghy.

I found the following work strategy practical :

- First pre-tin the components soldering islands on the PCB.
- Remove excess solder using a de-soldering wick. Remove the wick before the solder hardens

For each component, one soldering island will be used to pre-fix the component before definitive soldering. This island (*) should contain a bit more solder.

- Place a component in correct position. Without supplying extra solder, fix it by quickly flowing a little solder from the solder island to the component
- Check the correct position and correct it if needed.
- Apply solder to and flow the other contact.
- As last, apply a little solder to the first (*) contact to flow the solder there.

- All resistors R1//R2 can be pre-fixed to the 50 Ohm transmission line.
- Then all other sides soldered.
- Then the first sides soldered.

Good solder flow helps cooling the components when RF power is connected.

IC1 can be placed and pre-fixed by soldering pin4 first. Check correct position using a magnifying glass.
Then use a hot iron (350C) and a short, medium sized, solder tip. Tin the tip.

- QUICKLY overflow pins 1-3 with solder.
- Let cool down well.
- QUICKLY overflow pins 4-6 with solder.
- Let cool down well.
- QUICLY remove excess solder from pins 1-3 using fresh de-solder wick.
- Let cool down well.
- QUICLY remove excess solder from pins 4-6 using fresh de-solder wick.
- Let cool down well.

Inspect solder quality at IC1 using a magnifying glass.